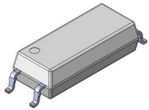


MECHANICAL CASE OUTLINE

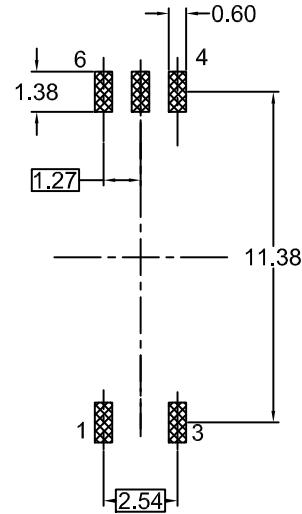
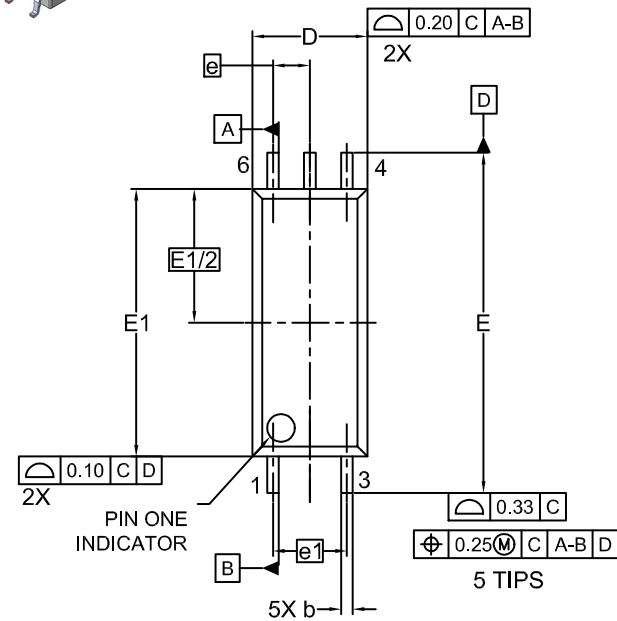
PACKAGE DIMENSIONS

ON Semiconductor®



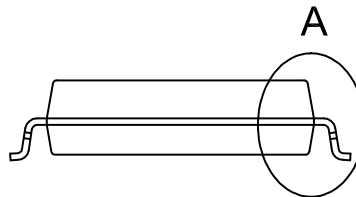
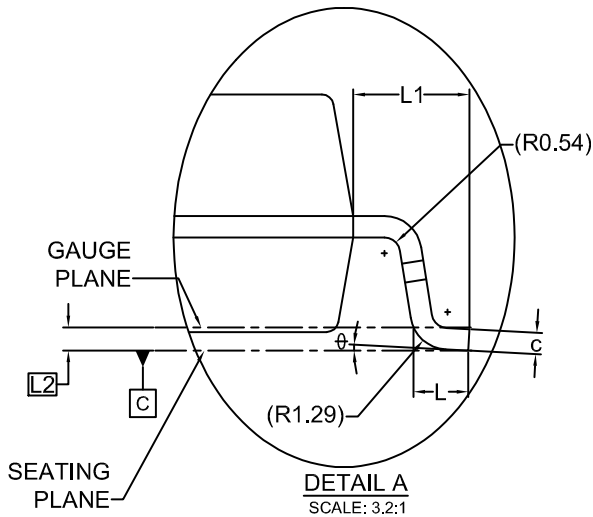
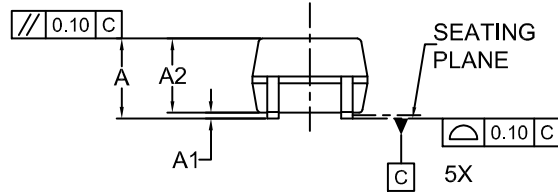
SOIC6 W LESS PIN 2 CASE 752AF ISSUE A

DATE 02 AUG 2021



LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE DOES NOT CONFORM TO ANY STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS
- D) DRAWING CONFORMS TO ASME Y14.5M-1994

DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	-	-	2.95
A1	0.10	0.20	0.30
A2	2.45	2.55	2.65
b	0.31	0.41	0.51
c	0.19	0.22	0.25
D	3.85	3.95	4.05
E	11.60	11.70	11.80
E1	9.10	9.20	9.30
E1/2	4.60 BSC		
e	1.27 BSC		
e1	2.54 BSC		
L	0.44	0.59	0.74
L1	1.15	1.25	1.35
L2	0.25 BSC		
ϕ	0°	-	8°

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